

ISL8700, ISL8701, ISL8702

Adjustable Quad Sequencer

FN9250
Rev 2.00
March 21, 2008

The ISL8700, ISL8701, ISL8702 family of ICs provide four delay adjustable sequenced outputs while monitoring an input voltage all with a minimum of external components.

High performance DSP, FPGA, μ P and various subsystems require input power sequencing for proper functionality at initial power-up and the ISL870x provides this function while monitoring the distributed voltage for over and undervoltage compliance.

The ISL8700 and ISL8701 operate over the +2.5V to +24V nominal voltage range, whereas the ISL8702 operates over the +2.5V to +12V nominal voltage range. All three have a user adjustable time from UV and OV voltage compliance to sequencing start via an external capacitor when in auto start mode and adjustable time delay to subsequent ENABLE output signal via external resistors.

Additionally, the ISL8702 provides an input for sequencing on and off operation (SEQ_EN) and for voltage window compliance reporting (FAULT) over the +2.5V to +12V voltage range.

Easily daisy chained for more than 4 sequenced signals.

Altogether, the ISL870x provides these adjustable features with a minimum of external BOM. See Figure 1 for typical implementation.

Ordering Information

PART NUMBER (Note)	PART MARKING	TEMP. RANGE (°C)	PACKAGE (Pb-free)	PKG. DWG. #
ISL8700IBZ*	ISL 8700IBZ	-40 to +85	14 Ld SOIC	M14.15
ISL8701IBZ*	ISL 8701IBZ	-40 to +85	14 Ld SOIC	M14.15
ISL8702IBZ*	ISL 8702IBZ	-40 to +85	14 Ld SOIC	M14.15
ISL870xEVAL1	Evaluation Platform			

*Add "-T" suffix for tape and reel. Please refer to TB347 for details on reel specifications.

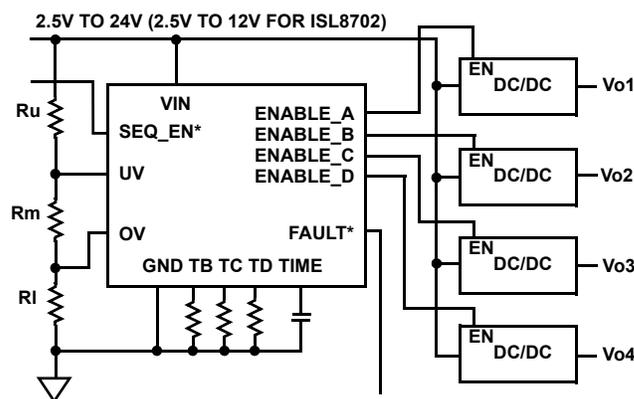
NOTE: These Intersil Pb-free plastic packaged products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate PLUS ANNEAL - e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

Features

- Adjustable Delay to Subsequent Enable Signal
- Adjustable Delay to Sequence Auto Start
- Adjustable Distributed Voltage Monitoring
- Undervoltage and Overvoltage Adjustable Delay to Auto Start Sequence
- I/O Options
ENABLE (ISL8700, ISL8702) and ENABLE# (ISL8701)
SEQ_EN (ISL8702)
- Voltage Compliance Fault Output
- Pb-Free (RoHS Compliant)

Applications

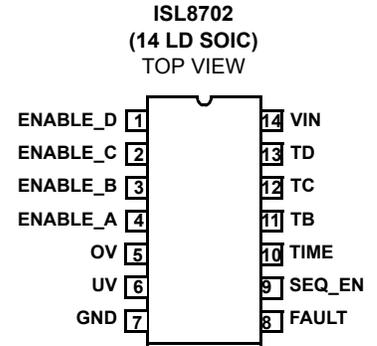
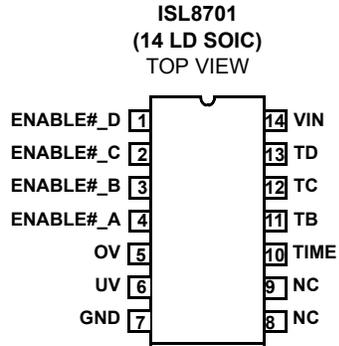
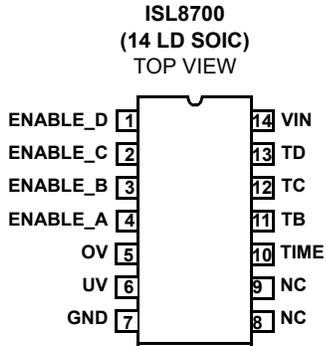
- Power Supply Sequencing
- System Timing Function



* SEQ_EN and FAULT are not available on ISL8700 and ISL8701

FIGURE 1. ISL870x IMPLEMENTATION

Pinouts



Absolute Maximum Ratings

ISL8700, ISL8701 V_{IN} , ENABLE(#), FAULT 27V, to -0.3V
 ISL8702 V_{IN} , ENABLE(#), FAULT 14V, to -0.3V
 TIME, TB, TC, TD, UV, OV +6V, to -0.3V
 SEQ_EN(#) $V_{IN}+0.3V$, to -0.3V
 ENABLE, ENABLE # Output Current 10mA

Operating Conditions

Temperature Range -40°C to +85°C
 Supply Voltage Range (Nominal) 2.5V to 24V
 ISL8702 Supply Voltage Range (Nominal) 2.5V to 12V

Thermal Information

Thermal Resistance (Typical, Note 1) θ_{JA} (°C/W)
 14 Ld SOIC 110
 Maximum Junction Temperature (Plastic Package) +125°C
 Maximum Storage Temperature Range -65°C to +150°C
 Pb-free Reflow Profile see link below
<http://www.intersil.com/pbfree/Pb-FreeReflow.asp>

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

NOTE:

1. θ_{JA} is measured with the component mounted on a high effective thermal conductivity test board in free air. See Tech Brief TB379 for details.

Electrical Specifications Nominal V_{IN} = 2.5V to +24V, $T_A = T_J = -40^\circ\text{C}$ to +85°C, Unless Otherwise Specified.
 ISL8702 V_{IN} = 2.5V to +12V

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
UV AND OV INPUTS						
UV/OV Rising Threshold	V_{UVRvth}		1.16	1.21	1.28	V
UV/OV Falling Threshold	V_{UVFvth}		1.06	1.10	1.18	V
UV/OV Hysteresis	V_{UVhys}	$V_{UVRvth} - V_{UVFvth}$	-	104	-	mV
UV/OV Input Current	I_{UV}		-	10	-	nA
TIME, ENABLE/ENABLE# OUTPUTS						
TIME Pin Charging Current	I_{TIME}		-	2.6	-	μA
TIME Pin Threshold	V_{TIME_VTH}		1.9	2.0	2.25	V
Time from V_{IN} Valid to ENABLE_A	$t_{VINSEQpd}$	SEQ_EN = high, C_{TIME} = open	-	30	-	μs
	$t_{VINSEQpd_10}$	SEQ_EN = high, C_{TIME} = 10nF	-	7.7	-	ms
	$t_{VINSEQpd500}$	SEQ_EN = high, C_{TIME} = 500nF	-	435	-	ms
Time from V_{IN} Invalid to Shutdown	$t_{shutdown}$	UV or OV to simultaneous shutdown	-	-	1	μs
ENABLE Output Resistance	R_{EN}	$I_{ENABLE} = 1\text{mA}$	-	100	-	Ω
ENABLE Output Low	V_{ol}	$I_{ENABLE} = 1\text{mA}$	-	0.1	-	V
ENABLE Pull-Down Current	I_{pulld}	ENABLE = 1V	10	15	-	mA
Delay to Subsequent ENABLE Turn-On/Off	t_{del_120}	$R_{TX} = 120\text{k}\Omega$	155	195	240	ms
	t_{del_3}	$R_{TX} = 3\text{k}\Omega$	3.5	4.7	6	ms
	t_{del_0}	$R_{TX} = 0\Omega$	-	0.5	-	ms
SEQUENCE ENABLE AND FAULT I/O						
V_{IN} Valid to FAULT Low	t_{FLTL}		15	30	50	μs
V_{IN} Invalid to FAULT High	t_{FLTH}		-	0.5	-	μs
FAULT Pull-down Current		FAULT = 1V	10	15	-	mA
SEQ_EN Pull-up Voltage	V_{SEQ}	SEQ_EN open	-	V_{IN}	-	V
SEQ_EN Low Threshold Voltage	V_{ilSEQ_EN}		-	-	0.3	V
SEQ_EN High Threshold Voltage	V_{ihSEQ_EN}		1.2	-	-	V
Delay to ENABLE_A Deasserted	$t_{SEQ_EN_ENA}$	SEQ_EN low to ENABLE_A low	-	0.2	1	μs

Electrical Specifications Nominal $V_{IN} = 2.5V$ to $+24V$, $T_A = T_J = -40^{\circ}C$ to $+85^{\circ}C$, Unless Otherwise Specified.
 ISL8702 $V_{IN} = 2.5V$ to $+12V$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
BIAS						
IC Supply Current	$I_{VIN_2.2V}$	$V_{IN} = 2.2V$	-	191	-	μA
	I_{VIN_12V}	$V_{IN} = 12V$	-	246	400	μA
	I_{VIN_24V}	$V_{IN} = 24V$	-	286	-	μA
V_{IN} Power On Reset	V_{IN_POR}	V_{IN} low to high	-	2.08	2.5	V

Pin Descriptions

PIN NUMBER			PIN NAME	FUNCTION DESCRIPTION
ISL8700	ISL8701	ISL8702		
NA	1	NA	ENABLE#_D	Active low open drain sequenced output. Sequenced on after ENABLE#_C and first output to sequence off for the ISL8701. Tracks V_{IN} upon bias.
1	NA	1	ENABLE_D	Active high open drain sequenced output. Sequenced on after ENABLE#_C and first output to sequence off for the ISL8700, ISL8702. Pulls low with $V_{IN} < 1V$.
NA	2	NA	ENABLE#_C	Active low open drain sequenced output. Sequenced on after ENABLE#_B and sequenced off after ENABLE#_D for the ISL8701. Tracks V_{IN} upon bias.
2	NA	2	ENABLE_C	Active high open drain sequenced output. Sequenced on after ENABLE#_B and sequenced off after ENABLE#_D for the ISL8700, ISL8702. Pulls low with $V_{IN} < 1V$.
NA	3	NA	ENABLE#_B	Active low open drain sequenced output. Sequenced on after ENABLE#_A and sequenced off after ENABLE#_C for the ISL8701. Tracks V_{IN} upon bias.
3	NA	3	ENABLE_B	Active high open drain sequenced output. Sequenced on after ENABLE#_A and sequenced off after ENABLE#_C for the ISL8700, ISL8702. Pulls low with $V_{IN} < 1V$.
NA	4	NA	ENABLE#_A	Active low open drain sequenced output. Sequenced on after CTIME period and sequenced off after ENABLE#_B for the ISL8701. Tracks V_{IN} upon bias.
4	NA	4	ENABLE_A	Active high open drain sequenced output. Sequenced on after CTIME period and sequenced off after ENABLE#_B for the ISL8700, ISL8702. Pulls low with $V_{IN} < 1V$.
5	5	5	OV	The voltage on this pin must be under its 1.22V V_{th} or the four ENABLE outputs will be immediately pulled down. Conversely the 4 ENABLE# outputs will be released to be pulled high via external pull ups.
6	6	6	UV	The voltage on this pin must be over its 1.22V V_{th} or the four ENABLE outputs will be immediately pulled down. Conversely the 4 ENABLE# outputs will be released to be pulled high via external pull ups.
7	7	7	GND	IC ground.
NA	NA	8	FAULT	The V_{IN} voltage when not within the desired UV to OV window will cause FAULT to be released to be pulled high to a voltage equal to or less than V_{IN} via an external resistor.
NA	NA	9	SEQ_EN	This pin provides a sequence on signal input with a high input. Internally pulled high to V_{IN} .
NA	NA	NA	SEQ_EN#	This pin provides a sequence on signal input with a low input. Internally pulled high to V_{IN} .
10	10	10	TIME	This pin provides a 2.6 μA current output so that an adjustable V_{IN} valid to sequencing on and off start delay period is created with a capacitor to ground.
11	11	11	TB	A resistor connected from this pin to ground determines the time delay from ENABLE#_A being active to ENABLE#_B being active on turn-on and also going inactive on turn-off via the SEQ_IN input.
12	12	12	TC	A resistor connected from this pin to ground determines the time delay from ENABLE#_B being active to ENABLE#_C being active on turn-on and also going inactive on turn-off via the SEQ_IN input.
13	13	13	TD	A resistor connected from this pin to ground determines the time delay from ENABLE#_C being active to ENABLE#_D being active on turn-on and also going inactive on turn-off via the SEQ_IN input.
14	14	14	V_{IN}	IC Bias Pin Nominally 2.5V to 24V (2.5V to 12V for ISL8702). This pin requires a 1 μF decoupling capacitor close to IC pin.

On the ISL8702, enabling of on or off sequencing can also be signaled via the SEQ_EN input pin once voltage compliance is met. Initially the SEQ_EN pin should be held low and released when sequence start is desired. The on sequence of the ENABLE outputs is as previously described. The off sequence feature is only available on the variants having the SEQ_EN or the SEQ_EN# inputs, this being the ISL8702. The sequence is D off, then C off, then B off and finally A off. Once SEQ_EN (SEQ_EN#) is signaled low (high) the TIME cap is charged to 2V once again. Once this V_{th} is reached ENABLE_D transitions to its reset state and CTIM is discharged. A delay and subsequent sequence off is then determined by TD resistor to ENABLE_C. Likewise, a delay to ENABLE_B and then ENABLE_A turn-off is determined by TC and TB resistor values respectively.

With the ISL8700, ISL8701, a quasi down sequencing of the ENABLE outputs can be achieved by loading the ENABLE pins with various value capacitors to ground. When a simultaneous output latch off is invoked, the caps will set the falling ramp of the various ENABLE outputs thus adjusting the time to V_{th} for various DC/DC converters or other circuitry.

Regardless of IC variant, the FAULT signal is always valid at operational voltages and can be used as justification for SEQ_EN release or even controlled with an RC timer for sequence on.

Programming the Undervoltage and Overvoltage Limits

When choosing resistors for the divider, remember to keep the current through the string bounded by power loss at the top end and noise immunity at the bottom end. For most applications, total divider resistance in the 10kΩ to 1000kΩ range is advisable with high precision resistors being used to reduce monitoring error. Although for the ISL870x two dividers of two resistors each can be employed to separately monitor the OV and UV levels for the V_{IN} voltage which will be discussed here using a single three resistor string for monitoring the V_{IN} voltage, referencing Figure 1. In the three resistor divider string with R_u (upper), R_m (middle) and R_l (lower), the ratios of each in combination to the other two is balanced to achieve the desired UV and OV trip levels. Although this IC has a bias range of 2.5V to 24V (12V for ISL8702), it can monitor any voltage >1.22V.

The ratio of the desired overvoltage trip point to the internal reference is equal to the ratio of the two upper resistors to the lowest (ground connected) resistor.

The ratio of the desired undervoltage trip point to the internal reference voltage is equal to the ratio of the uppermost (voltage connected) resistor to the lower two resistors.

These assumptions are true for both rising (turn-on) or falling (shutdown) voltages.

The following is a practical example worked out. For detailed equations on how to perform this operation for a given supply requirement, please refer to the next section.

1. Determine if turn-on or shutdown limits are preferred and in this example we will determine the resistor values based on the shutdown limits.
2. Establish lower and upper trip level: 12V ±10% or 13.2V (OV) and 10.8V (UV)
3. Establish total resistor string value: 100kΩ, I_r = divider current
4. (R_m + R_l) × I_r = 1.1V @ UV and R_l × I_r = 1.2V @ OV
5. R_m + R_l = 1.1V/I_r @ UV = R_m + R_l = 1.1V/(10.8V/100kΩ) = 10.370kΩ
6. R_l = 1.2V/I_r @ OV = R_l = 1.2V/(13.2V/100kΩ) = 9.242kΩ
7. R_m = 10.370kΩ - 9.242kΩ = 1.128kΩ
8. R_u = 100kΩ - 10.370kΩ = 89.630kΩ
9. Choose standard value resistors that most closely approximate these ideal values. Choosing a different total divider resistance value may yield a more ideal ratio with available resistors values.

In our example with the closest standard values of R_u = 90.9kΩ, R_m = 1.13kΩ and R_l = 9.31kΩ, the nominal UV falling and OV rising will be at 10.9V and 13.3V respectively.

An Advanced Tutorial on Setting UV and OV Levels

This section discusses in additional detail the nuances of setting the UV and OV levels, providing more insight into the ISL870x than the earlier text.

The following equation set can alternatively be used to work out ideal values for a 3 resistor divider string of R_u, R_m and R_l. These equations assume that V_{REF} is the center point between V_{UVRvth} and V_{UVFvth} (i.e. (V_{UVRvth} + V_{UVFvth})/2 = 1.17V), I_{load} is the load current in the resistor string (i.e. V_{IN}/(R_u + R_m + R_l)), V_{IN} is the nominal input voltage and V_{tol} is the acceptable voltage tolerance, such that the UV and OV thresholds are centered at V_{IN} ± V_{tol}. The actual acceptable voltage window will also be affected by the hysteresis at the UV and OV pins. This hysteresis is amplified by the resistor string such that the hysteresis at the top of the string is calculated in Equation 1:

$$V_{hys} = V_{UVhys} \times V_{OUT}/V_{REF} \quad (\text{EQ. 1})$$

This means that the V_{IN} ± V_{tol} thresholds will exhibit hysteresis resulting in thresholds of V_{IN} + V_{tol} ± V_{hys}/2 and V_{IN} - V_{tol} ± V_{hys}/2.

There is a window between the V_{IN} rising UV threshold and the V_{IN} falling OV threshold where the input level is guaranteed not to be detected as a fault. This window exists between the limits V_{IN} ± (V_{tol} - V_{hys}/2). There is an extension of this window in each direction up to V_{IN} ± (V_{tol} + V_{hys}/2), where the voltage may or may not be

detected as a fault, depending on the direction from which it is approached. These two equations may be used to determine the required value of V_{tol} for a given system. For example, if V_{IN} is 12V, $V_{hys} = (0.1 \times 12)/1.17 = 1.03V$. If V_{IN} must remain within $12V \pm 1.5V$, $V_{tol} = 1.5 - 1.03/2 = 0.99V$. This will give a window of $12 \pm 0.48V$ where the system is guaranteed not to be in fault and a limit of $12 \pm 1.5V$ beyond which the system is guaranteed to be in fault.

It is wise to check both these voltages for if the latter is made too tight, the former will cease to exist. This point comes when $V_{tol} < V_{hys}/2$ and results from the fact that the acceptable window for the OV pin no longer aligns with the acceptable window for the UV pin. In this case, the application will have to be changed such that UV and OV are provided separate resistor strings. In this case the UV and OV thresholds can be individually controlled by adjusting the relevant divider.

The previous example will give voltage thresholds:

with V_{IN} rising

$$V_r = V_{IN} - V_{tol} + V_{hys}/2 = 11.5V \text{ and} \quad (\text{EQ. 2})$$

$$V_r = V_{IN} + V_{tol} + V_{hys}/2 = 13.5V$$

with V_{IN} falling

$$V_f = V_{IN} + V_{tol} - V_{hys}/2 = 12.5V \text{ and} \quad (\text{EQ. 3})$$

$$V_f = V_{IN} - V_{tol} - V_{hys}/2 = 10.5V$$

So with a single three resistor string, the resistor values can be calculated using Equation 4:

$$R_l = (V_{REF}/I_{load})(1 - V_{tol}/V_{IN}) \quad (\text{EQ. 4})$$

$$R_m = 2(V_{REF} \times V_{tol})/(V_{IN} \times I_{load})$$

$$R_u = (1/I_{load}) \times (V_{IN} - V_{REF})(1 + V_{tol}/V_{IN})$$

For the above example with $V_{tol} = 0.99V$, assuming a $100\mu A$ I_{load} at $V_{IN} = 12V$:

$$R_l = 10.7k\Omega$$

$$R_m = 1.9k\Omega$$

$$R_u = 107.3k\Omega$$

Programming the ENABLE Output Delays

The delay timing between the four sequenced ENABLE outputs are programmed with four external passive components. The delay from a valid V_{IN} (ISL8700 and ISL8701) to ENABLE_A and SEQ_EN being valid (ISL8702) to ENABLE_A is determined by the value of the capacitor on the TIME pin to GND. The external TIME pin capacitor is charged with a $2.6\mu A$ current source. Once the voltage on TIME is charged up to the internal reference voltage, (V_{TIME_VTH}) the ENABLE_A output is released out of its reset state. The capacitor value for a desired delay ($\pm 10\%$) to ENABLE_A once V_{IN} and SEQ_EN where applicable has been satisfied is determined by using Equation 5:

$$C_{TIME} = t_{VINSEQpd}/770k\Omega \quad (\text{EQ. 5})$$

Once ENABLE_A reaches V_{TIME_VTH} , the TIME pin is pulled low in preparation for a sequenced off signal via SEQ_EN. At this time, the sequencing of the subsequent outputs is started. ENABLE_B is released out of reset after a programmable time, then ENABLE_C, then ENABLE_D, all with their own programmed delay times.

The subsequent delay times are programmed with a single external resistor for each ENABLE output providing maximum flexibility to the designer through the choice of the resistor value connected from TB, TC and TD pins to GND. The resistor values determine the charge and discharge rate of an internal capacitor comprising an RC time constant for an oscillator whose output is fed into a counter generating the timing delay to ENABLE output sequencing.

The R_{TX} value for a given delay time is defined as Equation 6:

$$R_{TX} = \frac{t_{del}}{1667nF} \quad (\text{EQ. 6})$$

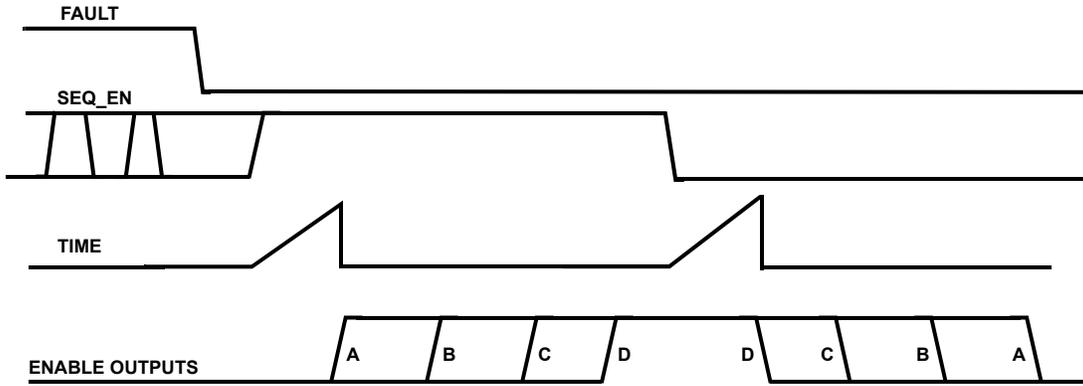


FIGURE 2. ISL8702 OPERATIONAL DIAGRAM

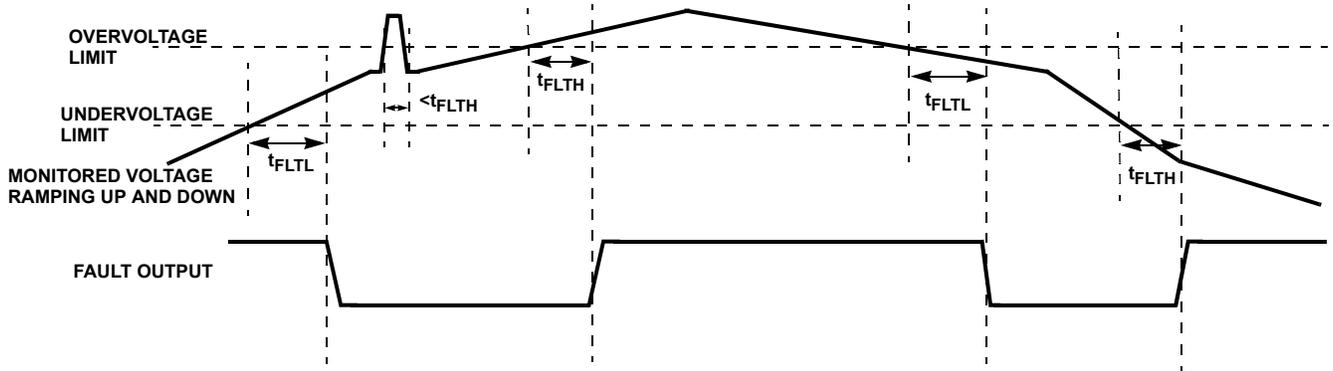


FIGURE 3. ISL8702 FAULT OPERATIONAL DIAGRAM

Typical Performance Curves

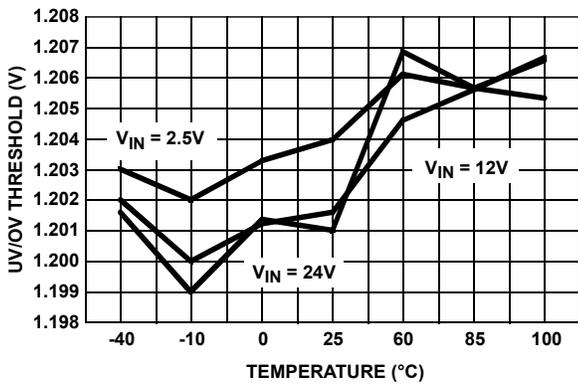


FIGURE 4. UV/OV RISING THRESHOLD

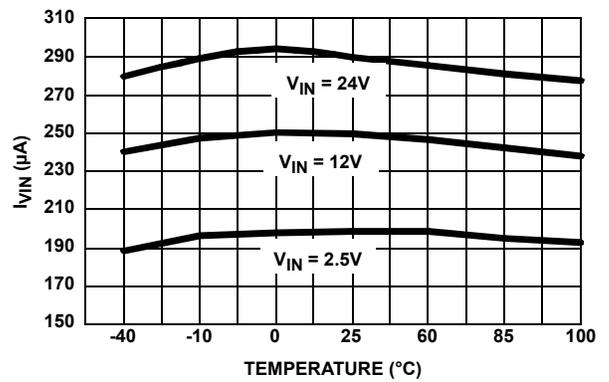


FIGURE 5. V_{IN} CURRENT

Applications Usage

Using the ISL870xEVAL1 Platform

The ISL870xEVAL1 platform is the primary evaluation board for this family of sequencers. See Figure 15 for a photograph and schematic. The evaluation board is shipped with an **ISL8702** mounted in the left position and with the other device variants loosely packed. In the following discussion, test points names are **bold** on initial occurrence for identification.

The **V_{IN}** test point is the chip bias and can be biased from 2.5V to 24V. The **V_{HI}** test point is for the ENABLE and **FAULT** pull-up voltage which are limited to a maximum of 24V independent of **V_{IN}**. The UV/OV resistor divider is set so that a nominal 12V on the **V_{MONITOR}** test point is compliant and with a rising OV set at 13.2V and a falling UV set at 10.7V. These three test points (**V_{IN}**, **V_{HI}** and **V_{MONITOR}**) are brought out separately for maximum flexibility in evaluation.

V_{MONITOR} ramping up and down through the UV and OV levels will result in the **FAULT** output signaling the out of

bound conditions by being released to pull high to the **V_{HI}** voltage as shown in Figures 6 and 7.

Once the voltage monitoring **FAULT** is resolved and where applicable, the **SEQ_EN(#)** is satisfied, sequencing of the **ENABLE_X(#)** outputs begins. When sequence enabled the **ENABLE_A**, **ENABLE_B**, **ENABLE_C** and lastly **ENABLE_D** are asserted in that order and when **SEQ_EN** is disabled, the order is reversed. See Figures 8 and 9 demonstrating the sequenced enabling and disabling of the **ENABLE** outputs. The timing between **ENABLE** outputs is set by the resistor values on the **TB**, **TC**, **TD** pins as shown. Figure 10 illustrates the timing from either **SEQ_EN** and/or **V_{MONITOR}** being valid to **ENABLE_A** being asserted with a 10nF **TIME** capacitor. Figure 11 shows that **ENABLE_X** outputs are pulled low even before **V_{IN} = 1V**. This is critical to ensure that a false enable is not signaled. Figure 12 shows the time from **SEQ_EN** transition with the voltage ramping across the **TIME** capacitor to **TIME V_{th}** being met. This results in the immediate pull down of the **TIME** pin and simultaneous **ENABLE_A** enabling. Figure 13 illustrates the immunity of the **UV** and **OV** inputs to transients.

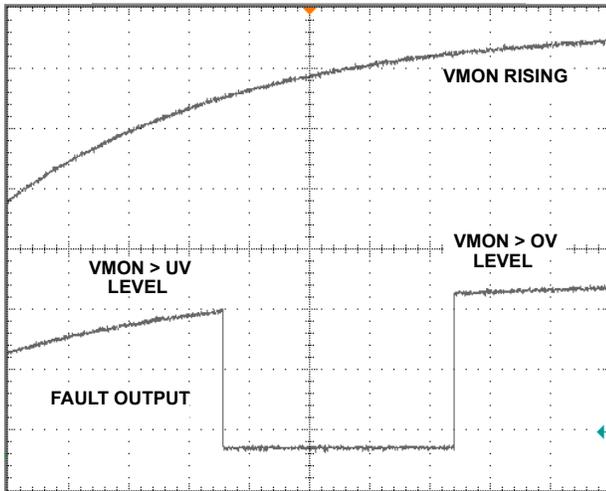


FIGURE 6. V_{MONITOR} RISING TO FAULT

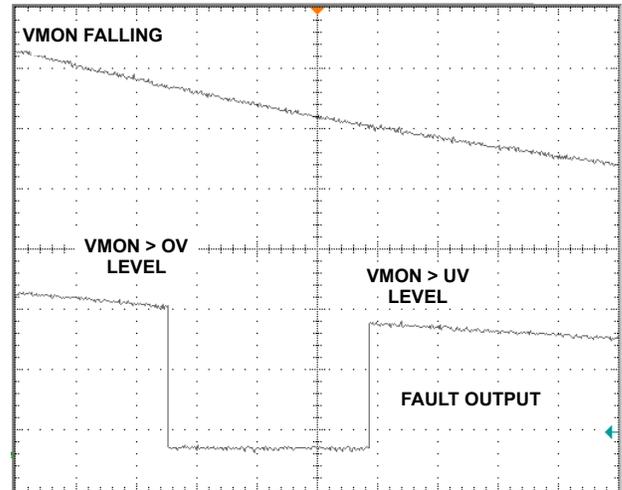


FIGURE 7. V_{MONITOR} FALLING TO FAULT

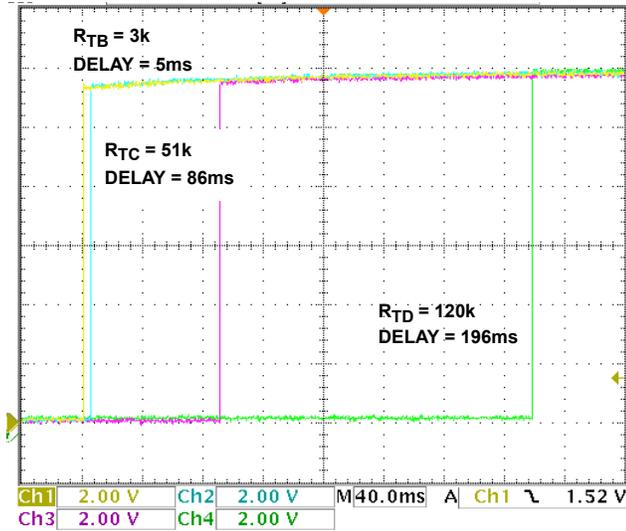


FIGURE 8. ENABLE_X TO ENABLE_X ENABLING

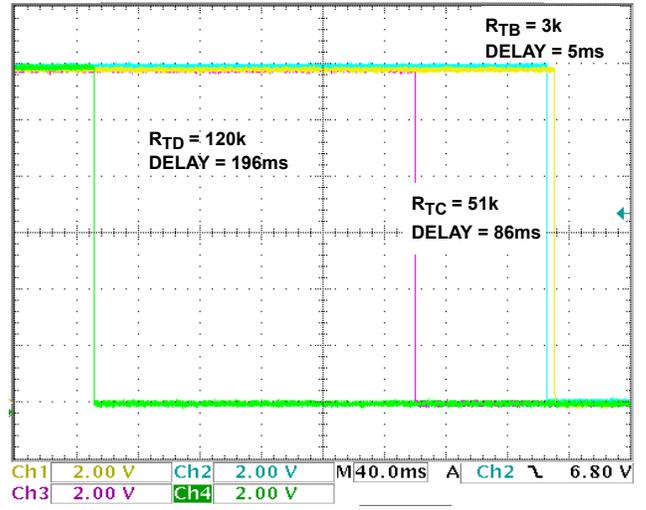


FIGURE 9. ENABLE_X TO ENABLE_X DISABLING

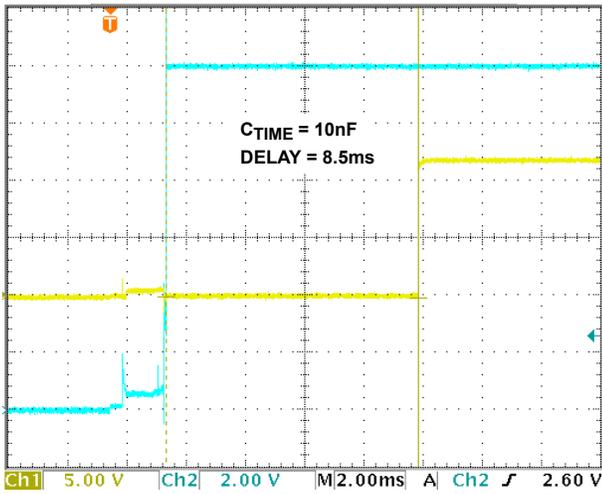


FIGURE 10. V_{IN}/SEQ_{EN} VALID TO ENABLE_A

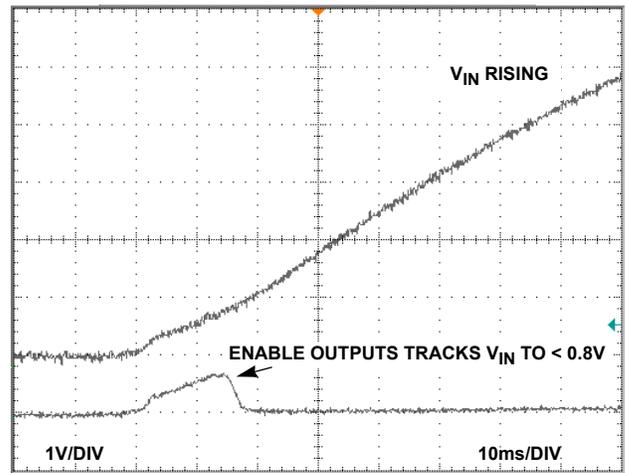


FIGURE 11. ENABLE AS V_{IN} RISES

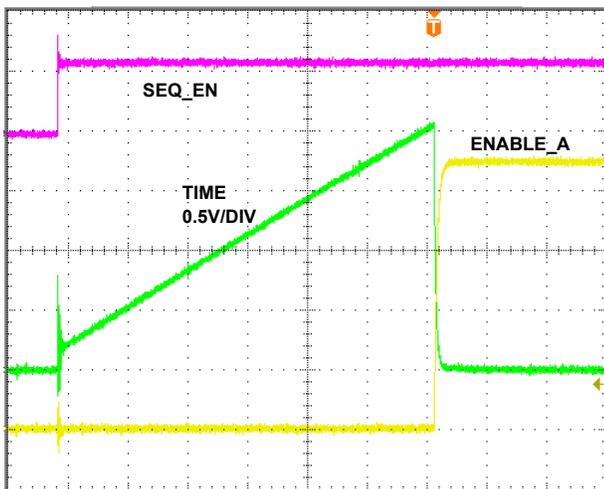


FIGURE 12. SEQ_EN TO ENABLE_A

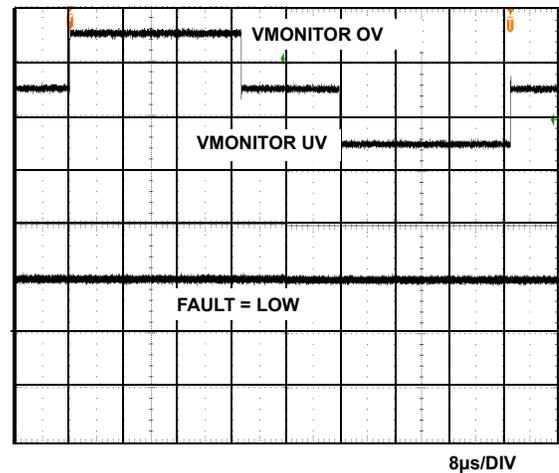


FIGURE 13. OV AND UV TRANSIENT IMMUNITY

Application Concerns and Recommendations

When designing the ISL8700 family of products into applications with low supply voltages such as 3.3V, additional filtering to help reduce system noise on the voltage supply input is necessary to ensure proper voltage sequencing operation. It is important that the user-programmed UV threshold is set sufficiently above (i.e. >200mV) the ISL8700 IC's internal POR level, V_{IN_POR} , over the entire operating temperature range. Best design practices include proper decoupling on the supply input (i.e. at least 1 μ F) as well as an RC filter that can adequately suppress noise on the supply in the user's application, whereby the resistor should be kept < 13 Ω to reduce voltage loss to the already low biased VIN pin.

Coupling from the ENABLE_X pins to the sensitive UV and OV pins can cause false OV/UV events to be detected. This is most relevant for ISL8700, ISL8702 parts due to the ENABLE_A and OV pins being adjacent. This coupling can be reduced by adding a ground trace between UV and the ENABLE/FAULT signals, as shown in Figure 14. The PCB traces on OV and UV should be kept as small as practical and the ENABLE_X and FAULT traces should ideally not be routed under/over the OV/UV traces on different PCB layers unless there is a ground or power plane in between. Other methods that can be used to eliminate this issue are by reducing the value of the resistors in the network connected to UV and OV (R_2 , R_3 , R_5 in Figure 15) or by adding small decoupling capacitors to OV and UV (C_2 and C_7 in Figure 15). Both these methods act to reduce the AC impedance at the nodes, although the latter method acts to filter the signals, which will also cause an increase in the time that a UV/OV fault takes to be detected.

When the ISL870x is implemented on a hot swappable card that is plugged into an always powered passive back plane, an RC filter is required on the V_{IN} pin to prevent a high dv/dt transient. With the already existing 1 μ F decoupling capacitor, the addition of a small series R (<13 Ω) to provide a time constant >50 μ s is all that is necessary.

Only the ISL8702 has a V_{IN} limitation of 14V maximum.

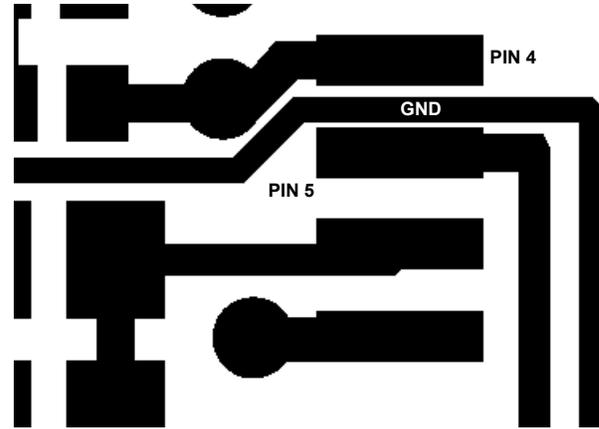


FIGURE 14. LAYOUT DETAIL OF GND BETWEEN PINS 4 AND 5

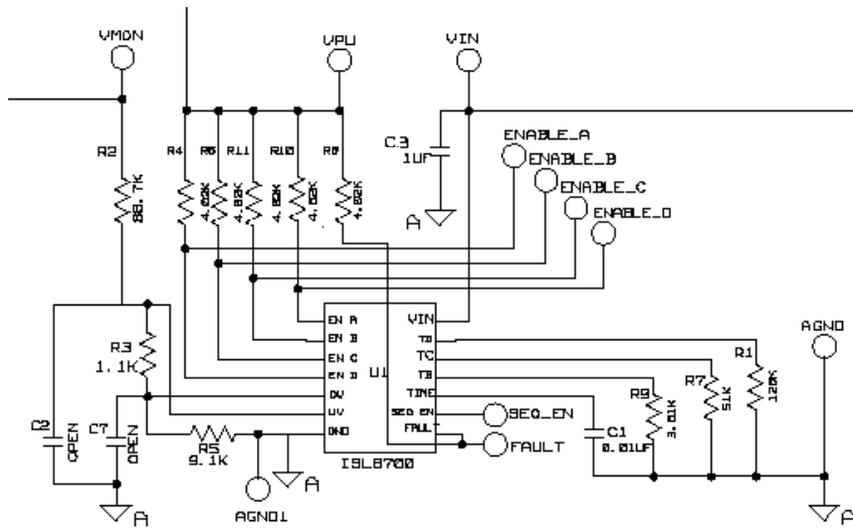
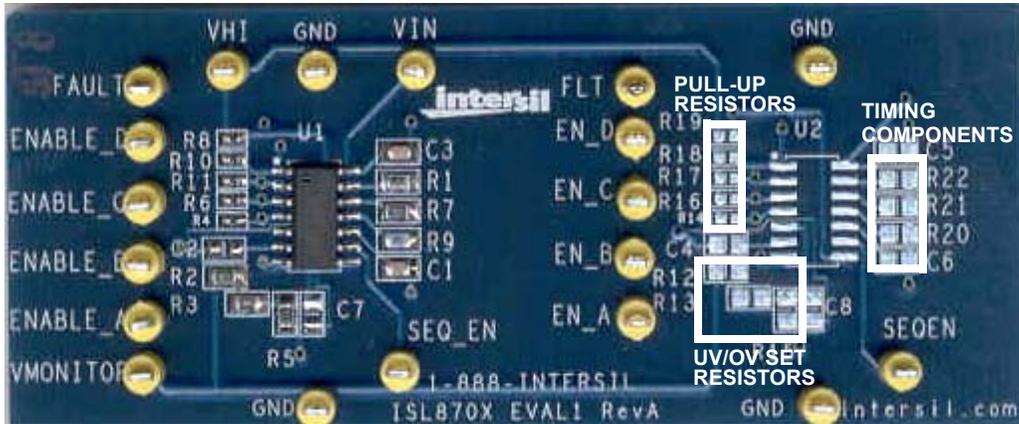
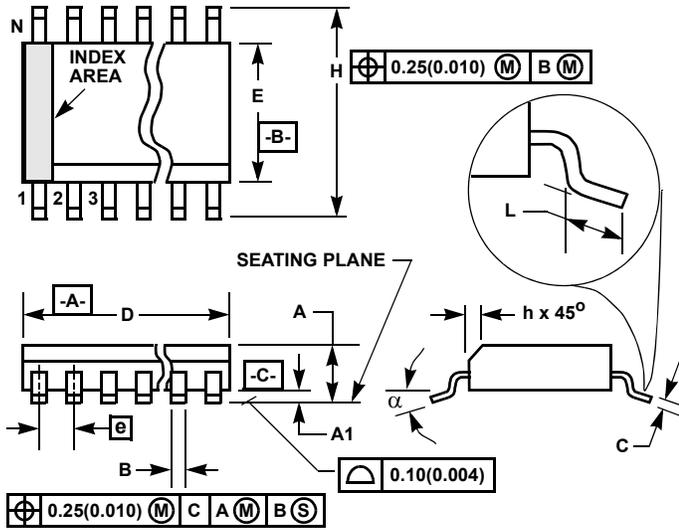


FIGURE 15. ISL870xEVAL1 PHOTOGRAPH AND SCHEMATIC OF LEFT CHANNEL

TABLE 1. ISL870xEVAL1 LEFT CHANNEL COMPONENT LISTING

COMPONENT DESIGNATOR	COMPONENT FUNCTION	COMPONENT DESCRIPTION
U1	ISL8702, Quad Under/Overvoltage Sequencer	Intersil, ISL8702, Quad Undervoltage, Overvoltage Sequencer
R3	UV Resistor for Divider String	1.1kΩ 1%, 0603
R2	VMONITOR Resistor for Divider String	88.7kΩ 1%, 0603
R5	OV Resistor for Divider String	9.1kΩ 1%, 0603
C1	C _{TIME} Sets Delay from Sequence Start to First ENABLE	0.01μF, 0603
R1	R _{TD} Sets Delay from Third to Fourth ENABLE	120kΩ 1%, 0603
R9	R _{TB} Sets Delay from First to Second ENABLE	3.01kΩ 1%, 0603
R7	R _{TC} Sets Delay from Second to Third ENABLE	51kΩ 1%, 0603
R4, R6, R8, R10, R11	ENABLE_X(#) and FAULT Pull-up Resistors	4kΩ 10%, 0402
C3	Decoupling Capacitor	1μF, 0603

Small Outline Plastic Packages (SOIC)



**M14.15 (JEDEC MS-012-AB ISSUE C)
14 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0532	0.0688	1.35	1.75	-
A1	0.0040	0.0098	0.10	0.25	-
B	0.013	0.020	0.33	0.51	9
C	0.0075	0.0098	0.19	0.25	-
D	0.3367	0.3444	8.55	8.75	3
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		-
H	0.2284	0.2440	5.80	6.20	-
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	14		14		7
alpha	0°	8°	0°	8°	-

NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

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